

CONTAMINATION STUDY OF SPACE SENSITIVE SURFACES BY PACKAGING MATERIALS

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MOTIVATION

Cleanliness is crucial for space hardware : the presence of contaminants, either organic residues or particles, on sensitive parts such as optics, mechanisms, detectors, electronics or thermal control coatings may alter significantly their properties and their nominal operating mode. Even if the AIT activities take place in controlled environments, it is highly recommended to protect the equipment during long-term storage and sometimes during short-term periods as well and of course during the numerous shipments in containers. Special care has to be taken to the packaging constraints that are dependent on the cleanliness specifications of the sensitive surfaces to be protected. Further to several anomalies and some alerts coming to the user community, the cross contamination due to materials and/or packaging methods is a real concern. Despite the guidelines described in standards, it still happens that some packaging materials are poorly known and therefore misused.

The purpose of this benchmark study was to develop a methodology and measurement protocols to assess the risk of molecular and/or particulate contamination on different substrates from a wide variety of flexible and rigid packaging materials, in stress conditions or not, in order to the user to select the



appropriate choice of packaging according to the part to be protected elaboration of a blister prototype packaging for sensitive devices

nples of sensitive equipment before and after integration on satellite protected for short or long-term storage most appropriate one for his dedicated applications. initial state substrates METHODOLOGY control SELECTED MATERIALS The second conditioning Shaking via back-and-forth table (120 strokes/min, 30 min) Low Density Polyethylene, Ultra Low Outgassing ISO 5 – 50 A/10 (STD 1246E) Space, Microelectronics, Varum anolicitations Low Density Polyethylene <u>Heating in oven (60°C, 2 days)</u> Long term exposure (room temperature, 2 months) storage/stress ISO 5 - 6
Medical, Pharma, Space, Microelectronics final state PE-AI (JPL antistatic LDPE extracti solution control particulate Al-Low Density Polyethylene · Low Density Polyethylene contamination polyethylene • Air tightness • ISO 6 • Medical, Pha Moisture barrier ESD S20.20, EN 61340-5-1 Antistatic additive ESD S20.20, EN 61340-5-1 Space, Micro ANALY SF polyethylene terephtalate glycol
ISO 7
Medical Dt- Membranes: phthalate
Part holding during transport
Space, Microelectronics molecular ng during transport tronics. Space contamination extractio part to analyse RANKING MAIN RESULTS particulate contamination tests Pink poly ULO ULO JPL film Poly alu Wafe ark of witness packaging samples nount of ppm added on silica substrates, after exposure in the various packaging samples Concentrations in ppn LDPE EAE нор box articulate contaminati 19 2 31 36 75 453 of witness packaging 1 6 6 2 186 samples ote ntaminatio f packaging samples afte exposure by shaking 1 1 2 з 5 8 16 27 66 300 224 200 articulate contamination 4 11 12 31 of SiO₂ substrates after 0 1 0 0 6 5 15 ire (shak of DRE Date CAL Dat 13 44 153 708 otal evaluation 56 6 7 8 10 11 Ranking 1 3 4 5 9 Lov High con atina molecular contamination tests olecular contamination from the Volatile molecular co on from the packaging Mem ULC Pink JPL film Vafe packaging samples sample EAE LDPE HDPE brane in µg/cm² poly poly box after solvent leaching and GC/MS analysis Surface molecular 0,8 0,7 0,6 0,5 0,4 0,3 0,2 0 0,538 105,3 ion in µg/cm2 0,004 0,02 0,04 0,05: 0,26 0,29 0,553 ntamination of witn 0.05 packaging samples 0,04 0,03 contamination of witnes 0,02 0,005 0,036 0,003 0 0,046 0,053 0,010 0,067 0,04 packaging samples ilar contar 0.01 0 0,004 0,027 0,044 0,051 of SiO₂ substrates after C 0 С 0 0 0,03 0 0,01 0 0,05 EAEbas LDPE bas exposure (60°C, 2 days) CAEDOR LOPE Date DON DAS WATER DOT ANARE DO' HOREDAN MONTHE DO IPL BIO NOW DE Blister otal evaluatio 105,39 Ranking 1 2 3 4 5 6 7 8 9 10 Volatile molecular contamination from the substrates after heated exposure in the various packaging sample Volatile molecular contamination from the substrates, after exposure in the various packaging samples during 2 months 0.05 ation in µg/cm2 0,04 Bag : pink poly, LDPE, EAE 0,03 (\mathfrak{R}) Bag : HDPE, PE-Al, ULO -poly 0,0 Box : membrane box or -nylon Box : blister 0.01 **Perspectives**

- ECSS-Q-ST-20-08C, Storage, handling and transportation of spacecraft hardware, 2014
 - ECSS-U-SI-2U-U8C, Storage, handling and transportation of spacecraft hardware, 2014 S. Lin, S. Graves, Comparing the molecular contamination contribution of clean packaging films, MICRO, Volume 16, Number 9, pp. 95-106, 1998 Lockheed Martin, General requirements and commercial packaging, P-40, Revision 6, 2012 L. Elena, Contamination of sensitive components by packaging materials, *CNES internship report*, 2015